



Winbond Electronics Corporation

6F., No.38, Gaotie 1st Rd., Jhubei City,
Hsinchu County 30273, Taiwan R.O.C.

Product Obsolescence Notice

W25Q16JL SpiFlash Memories

Notification Date: July 6, 2017

Dear Valued Customer,

This letter is to notify you of Winbond’s intention to terminate production of the W25Q16CL SpiFlash memory, and replace it with the W25Q16JL. Replacement part numbers are listed below:

Winbond Current PN (90nm C-Series)	Winbond Primary Replacement PN (58nm J-Series)
W25Q16CLSNIG	W25Q16JLSNIG
W25Q16CLZPIG	W25Q16JLZPIG
W25Q16CLSSIG	W25Q16JLSSIG
W25Q16CLSVIG	W25Q16JLSVIG

The W25Q16JL device features:

Features

- a) Command backward compatible with W25Q16CL
- b) Clock operation up to 104MHz
- c) Lower power consumption
- d) SPI with Single / Dual / Quad
- e) Flexible architecture with 4KB sectors

Please refer to the table below for your particular product last time order date and Winbond last shipment date and use this table to determine your last time buys and subsequent request dates. Winbond Electronics reserves the right to limit last time buy quantities based on capacity and material availability. Please notify Winbond as soon as possible if there are any concerns with these this schedule.

Part Number	Notification Date	Last Order Date	Last Ship Date	Part Number	Reliability Report	Mass Production
W25Q16CL	Jul./6/ 2017	Jan./6/ 2018	Jul./6/ 2018	W25Q16JL	Jun./26/ 2017	Jun./26/ 2017

Eddy Hung

Assistant Vice President of Flash Marketing



Product / Process Change Notice

No.: Z200-PCN-DM201707-01-A

Date: 07/10/2017

Change Title : W25Q16JL "J-Series" (58nm) to replace W25Q16CL "C-Series" (90nm) 16Mb SpiFlash® Memories

Change Classification: Major Minor

Change item : Design Raw Material Wafer FAB Assembly Packing Testing Others

Affected Product(s) :

W25Q16CLSNG , W25Q16CLSSIG , W25Q16CLSVIG , W25Q16CLZPIG ,

Description of Change(s)

The W25Q16JL 16Mb SpiFlash® Memories use Winbond's 58nm Flash technology. It is function-compatible W25Q16CL 90nm devices offering improved performance, features and availability. (refer the W25Q16JL and W25Q16CL Comparison in detail)

Reason for Change(s) :

Improve features and Command backward compatible with W25Q16CL.

Impact of Change(s) : (positive & negative)

Form : No Change

Fit : No Change

Function : No Concern (Please refer to attachment I)

Reliability : No Concern (Please refer to attachment II)

Hazardous Substances: No Concern (Please refer to attachment III)

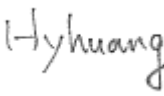


Qualification Plan/ Results :

Based on Winbond W25Q16JL Serial Flash Reliability report, the new product meets our criteria and no quality concern (refer to Reliability Report in details)

Implementation Plan :

Please refer to Attachment IV for details.

Date Code: ____ onward Lot No: ____ onward Proposed first ship date: Refer to Attachment IV for details

Originator: (QA)		Approval: (QA Dept. Manager)		Approval: (QRA Director)	
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Contact for Questions & Concerns	Name: <u>Betty Huang</u> TEL: <u>886-3-5678168</u> (ext.86549) FAX: <u>886-3-5796124</u>
	Address : <u># 539, Sec. 2, Wenxing Rd., Jhubei City, Hsinchu County 302, Taiwan</u>
	E-mail: <u>Hyhuang8@winbond.com</u>



Customer Comments:

Note: Please sign this notice, and return to Winbond contact within 30 days. If no response is received within 30 days, this Change Request will be assumed to meet your approval.

Approval Disapproval Conditional Approval : _____.

Comment:

Date: _____

Dept. name: _____

Person in charge: _____